

1103436

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DIN rail housing, Lower housing part with metal foot catch, with vents, width: 37.89 mm, height: 120.6 mm, depth: 82.85 mm, color: light gray (similar RAL 7035), cross connection: DIN rail connector (optional), number of positions cross connector: 5 or 8

Your advantages

- · Easy, tool-free mounting
- · Optional DIN rail connector for easy module-to-module communication
- · Lock and Release principle for automatic latching and intuitive release of the front connection plug
- · Plastic in accordance with UL94 V0: for more rigorous flammability requirements
- · L-design: ideal for flush integration of standard interfaces such as RJ45
- · Versatile use: deeper design for more PCB space
- · Greater flexibility: combination with ICS series electronics housing using DIN rail connectors

Commercial data

Item number	1103436
Packing unit	5 pc
Minimum order quantity	5 pc
Sales key	AC15
Product key	ACHEBA
GTIN	4055626964935
Weight per piece (including packing)	56.19 g
Weight per piece (excluding packing)	38.71 g
Customs tariff number	85389099
Country of origin	CN



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Technical data

Notes

Assembly note	Refer to the data sheet for the range in the download area.
Recommendation	Material of contact pads for bus connector, galvanic gold (hard gold)

Product properties

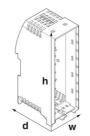
Enclosure bottom part
DIN rail housing
ME-IO
60 (pitch: 3.45 mm)
40 (pitch: 5 mm)
Lower housing part with metal foot catch
yes

Data management status

Dimensional drawing

Article revision	01

Dimensions



Width	37.89 mm
Height	120.6 mm
Depth	82.85 mm
Depth from top edge of DIN rail	76.25 mm

PCB design

PCB thickness	1.4 mm 1.8 mm
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Material specifications

Color (Housing)	light gray (RAL 7035)
Flammability rating according to UL 94	V0
CTI according to IEC 60112	600
Housing material	Polyamide
Surface characteristics	untreated

Environmental and real-life conditions



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Power dissipation single housing for 20 °C	
Ambient temperature	20 °C
Reduction factor	1
Mounting position	vertical
Power dissipation	18.45 W
Power dissipation single housing for 30 °C	
Ambient temperature	30 °C
Reduction factor	0.83
Mounting position	vertical
Power dissipation	15.3 W
Power dissipation single housing for 40 °C	
Ambient temperature	40 °C
Reduction factor	0.64
Mounting position	vertical
Power dissipation	11.88 W
Power dissipation single housing for 50 °C	
Ambient temperature	50 °C
Reduction factor	0.5
Mounting position	vertical
Power dissipation	9.18 W
Power dissipation single housing for 60 °C	
Ambient temperature	60 °C
Reduction factor	0.3
Mounting position	vertical
Power dissipation	5.85 W
Vibration test	
Specification	IEC 60068-2-6:2007-12
Frequency	10 - 150 - 10 Hz
Sweep speed	1 octave/min
Amplitude	0.15 mm (10 Hz 58.1 Hz)
Acceleration	2g (58.1 Hz 150 Hz)
Test duration per axis	2.5 h
Test directions	X-, Y- and Z-axis
Glow-wire test	
Specification	IEC 60695-2-11:2014-02
Temperature	850 °C
Time of exposure	30 s
Thermal stability / ball thrust test	
Specification	IEC 60695-10-2:2014-02
Temperature	125 °C
Tomporature	IZU U



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Specification IEC 60068-2-31:2008-05 Height of fall 50 cm	Test duration	1 h
Height of fall 50 cm	Force	20 N
Height of fall 50 cm Frequency 50 Shocks Specification IEC 60068-2-27:2008-02 Pulse shape Semi-sinusoidal Acceleration 15g Shock duration 11 ms Number of shocks per direction 3 Test directions X-, Y- and Z-axis (pos. and neg.) Flest for substances that would hinder coating with paint or varnish Specification VDMA 24364:2018-05 Degree of protection (IP code) Specification IEC 60529:1989-11 + AMD 1:1999-11 + AMD 2:2013-01 Ambient conditions Max. IP code to attain IP20 Ambient temperature (operation) 40 °C 105 °C (depending on power dissipation) Ambient temperature (storage/transport) 40 °C 55 °C Ambient temperature (storage/transport) 80 % B data Number of PCB holders 2 Type of PCB mount Latching Total PCB surface 14200 mm² Tickness of the PCB 100 m² Thickness of the PCB 118 mm Mounting type DIN rail mounting Kaging specifications Type of packaging packed in cardboard	Mechanical strength / tumbling barrel	
Shocks Specification IEC 60068-2-27:2008-02 Pulse shape Semi-sinusoidal Acceleration 15g Shock duration 11 ms Number of shocks per direction 3 Test directions X-, Y- and Z-axis (pos. and neg.) Fest for substances that would hinder coating with paint or varnish Specification VDMA 24364:2018-05 Degree of protection (IP code) Specification IEC 60529:1989-11 + AMD 1:1999-11 + AMD 2:2013-01 Ambient conditions Max. IP code to attain IP20 Ambient temperature (operation) -40 °C 105 °C (depending on power dissipation) Ambient temperature (storage/transport) -5 °C 100 °C Relative humidity (storage/transport) 20 °C Be data Number of PCB holders 2 Type of PCB mount Latching Total PCB surface 14200 mm² Thickness of the PCB 1.4 mm 1.8 mm Mounting type DIN rail mounting Kaging specifications Type of packaging specifications	Specification	IEC 60068-2-31:2008-05
Specification IEC 60068-2-27:2008-02 Pulse shape Semi-sinusoidal Acceleration 15g Shock duration 11 ms Number of shocks per direction 3 Test directions X-, Y- and Z-axis (pos. and neg.) Fest for substances that would hinder coating with paint or varnish Specification VDMA 24364:2018-05 Degree of protection (IP code) Specification IEC 60529:1989-11 + AMD 1:1999-11 + AMD 2:2013-01 Ambient conditions Max. IP code to attain IP20 Ambient temperature (operation) -40 °C 105 °C (depending on power dissipation) Ambient temperature (storage/transport) -40 °C 55 °C Ambient temperature (assembly) -5 °C 100 °C Relative humidity (storage/transport) 80 % B data Number of PCB holders 2 Type of PCB mount Latching Total PCB surface 14200 mm² Thickness of the PCB 1.4 mm 1.8 mm Duruting Mounting type DIN rail mounting Ckaging specifications Type of packaging packed in cardboard	Height of fall	50 cm
Specification IEC 60068-2-27:2008-02 Pulse shape Semi-sinusoidal Acceleration 15g Shock duration 11 ms Number of shocks per direction 3 Test directions X-, Y- and Z-axis (pos. and neg.) Fest for substances that would hinder coating with paint or varnish Specification VDMA 24364:2018-05 Degree of protection (IP code) Specification IEC 60529:1989-11 + AMD 1:1999-11 + AMD 2:2013-01 Ambient conditions Max. IP code to attain IP20 Ambient temperature (operation) -40 °C 105 °C (depending on power dissipation) Ambient temperature (storage/transport) -40 °C 55 °C Ambient temperature (assembly) -5 °C 100 °C Relative humidity (storage/transport) 80 % B data Number of PCB holders 2 Type of PCB mount Latching Total PCB surface 14200 mm² Thickness of the PCB 1.4 mm 1.8 mm Jounting Mounting type DIN rail mounting Ckaging specifications Type of packaging packed in cardboard	Frequency	50
Pulse shape Acceleration 15g Shock duration 111 ms Number of shocks per direction 3 Test directions X-, Y- and Z-axis (pos. and neg.) Fest for substances that would hinder coating with paint or varnish Specification VDMA 24364:2018-05 Degree of protection (IP code) Specification IEC 60529:1989-11 + AMD 1:1999-11 + AMD 2:2013-06 Ambient conditions Max. IP code to attain Ambient temperature (operation) Ambient temperature (storage/transport) Ambient temperature (storage/transport) Ambient temperature (assembly) -5 °C 100 °C Relative humidity (storage/transport) 80 % B data Number of PCB holders Type of PCB mount Total PCB surface Thickness of the PCB 1.4 mm 1.8 mm Mounting type DIN rail mounting Mounting type Ckaging specifications Type of packaging packed in cardboard	Shocks	
Acceleration 15g Shock duration 11 ms Number of shocks per direction 3 Test directions X-, Y- and Z-axis (pos. and neg.) Fest for substances that would hinder coating with paint or varnish Specification VDMA 24364:2018-05 Degree of protection (IP code) Specification IEC 60529:1989-11 + AMD 1:1999-11 + AMD 2:2013-01 Ambient conditions Max. IP code to attain IP20 Ambient temperature (operation) 40 °C 105 °C (depending on power dissipation) Ambient temperature (storage/transport) 40 °C 55 °C Ambient temperature (assembly) -5 °C 100 °C Relative humidity (storage/transport) 80 % B data Number of PCB holders 2 Type of PCB mount Latching Total PCB surface 14200 mm² Thickness of the PCB 1.4 mm 1.8 mm Mounting type DIN rail mounting Ckaging specifications Type of packaging packed in cardboard	Specification	IEC 60068-2-27:2008-02
Shock duration 11 ms Number of shocks per direction 3 Test directions X-, Y- and Z-axis (pos. and neg.) Fest for substances that would hinder coating with paint or varnish Specification VDMA 24364:2018-05 Degree of protection (IP code) Specification IEC 60529:1989-11 + AMD 1:1999-11 + AMD 2:2013-06 Ambient conditions Max. IP code to attain IP20 Ambient temperature (operation) -40 °C 105 °C (depending on power dissipation) Ambient temperature (assembly) -5 °C 100 °C Relative humidity (storage/transport) 80 % B data Number of PCB holders 2 Type of PCB mount Latching Total PCB surface 14200 mm² Thickness of the PCB 1.4 mm 1.8 mm Sunting Mounting type DIN rail mounting Ckaging specifications Type of packaging packed in cardboard	Pulse shape	Semi-sinusoidal
Number of shocks per direction 3 Test directions X-, Y- and Z-axis (pos. and neg.) Test for substances that would hinder coating with paint or varnish Specification VDMA 24364:2018-05 Degree of protection (IP code) Specification IEC 60529:1989-11 + AMD 1:1999-11 + AMD 2:2013-06 Ambient conditions Max. IP code to attain IP20 Ambient temperature (operation) 40 °C 105 °C (depending on power dissipation) Ambient temperature (storage/transport) 40 °C 55 °C Ambient temperature (assembly) 5° °C 100 °C Relative humidity (storage/transport) 80 % And Company	Acceleration	15g
Test directions X-, Y- and Z-axis (pos. and neg.) Fest for substances that would hinder coating with paint or varnish Specification VDMA 24364:2018-05 Degree of protection (IP code) Specification IEC 60529:1989-11 + AMD 1:1999-11 + AMD 2:2013-01 Ambient conditions Max. IP code to attain IP20 Ambient temperature (operation) -40 °C 105 °C (depending on power dissipation) Ambient temperature (storage/transport) -5 °C 100 °C Relative humidity (storage/transport) 80 % B data Number of PCB holders 2 Type of PCB mount Latching Total PCB surface 14200 mm² Thickness of the PCB 1.4 mm 1.8 mm Punting Mounting type DIN rail mounting Ckaging specifications Type of packaging packed in cardboard	Shock duration	11 ms
Fest for substances that would hinder coating with paint or varnish Specification VDMA 24364:2018-05 Degree of protection (IP code) Specification IEC 60529:1989-11 + AMD 1:1999-11 + AMD 2:2013-01 Ambient conditions Max. IP code to attain Ambient temperature (operation) Ambient temperature (storage/transport) Ambient temperature (storage/transport) Ambient temperature (assembly) -5 ° C 100 ° C Relative humidity (storage/transport) 80 % B data Number of PCB holders 7 type of PCB mount Total PCB surface Thickness of the PCB 1.4 mm 1.8 mm Dunting Mounting type DIN rail mounting Ckaging specifications Type of packaging packed in cardboard	Number of shocks per direction	3
Specification VDMA 24364:2018-05 Degree of protection (IP code) Specification IEC 60529:1989-11 + AMD 1:1999-11 + AMD 2:2013-06 Ambient conditions Max. IP code to attain IP20 Ambient temperature (operation) -40 °C 105 °C (depending on power dissipation) Ambient temperature (storage/transport) -5 °C 100 °C Relative humidity (storage/transport) 80 % B data Number of PCB holders 2 Type of PCB mount Latching Total PCB surface 14200 mm² Thickness of the PCB 1.4 mm 1.8 mm DIN rail mounting Mounting type DIN rail mounting ckaging specifications Type of packaging packed in cardboard	Test directions	X-, Y- and Z-axis (pos. and neg.)
Specification VDMA 24364:2018-05 Degree of protection (IP code) Specification IEC 60529:1989-11 + AMD 1:1999-11 + AMD 2:2013-06 Ambient conditions Max. IP code to attain IP20 Ambient temperature (operation) -40 °C 105 °C (depending on power dissipation) Ambient temperature (storage/transport) -5 °C 100 °C Relative humidity (storage/transport) 80 % B data Number of PCB holders 2 Type of PCB mount Latching Total PCB surface 14200 mm² Thickness of the PCB 1.4 mm 1.8 mm DIN rail mounting Mounting type DIN rail mounting ckaging specifications Type of packaging packed in cardboard	est for substances that would hinder coating with paint or	varnish
Ambient conditions Max. IP code to attain Ambient temperature (operation) Ambient temperature (storage/transport) Ambient temperature (assembly) Relative humidity (storage/transport) Number of PCB holders Type of PCB mount Total PCB surface Thickness of the PCB Mounting Mounting type Ckaging specifications Type of packaging IP20 -40 °C 105 °C (depending on power dissipation) -40 °C 55 °C -40 °C		
Ambient conditions Max. IP code to attain Ambient temperature (operation) Ambient temperature (storage/transport) Ambient temperature (assembly) Relative humidity (storage/transport) Number of PCB holders Type of PCB mount Total PCB surface Thickness of the PCB Mounting Mounting type Ckaging specifications Type of packaging IP20 -40 °C 105 °C (depending on power dissipation) -40 °C 55 °C -40 °C	Degree of protection (IP code)	
Ambient conditions Max. IP code to attain Ambient temperature (operation) Ambient temperature (storage/transport) Ambient temperature (assembly) Ambient temperature (assembly) Relative humidity (storage/transport) B data Number of PCB holders Type of PCB mount Total PCB surface Thickness of the PCB Mounting Mounting type DIN rail mounting Ckaging specifications Type of packaging packed in cardboard		IEC 60520:4000 44 + AMD 4:4000 44 + AMD 0:0040 0
Max. IP code to attain IP20 Ambient temperature (operation) Ambient temperature (storage/transport) Ambient temperature (storage/transport) Ambient temperature (assembly) -5°C 100°C Relative humidity (storage/transport) 80 % CB data Number of PCB holders Type of PCB mount Total PCB surface Thickness of the PCB 1.4 mm 1.8 mm DIN rail mounting Mounting type Ckaging specifications Type of packaging packed in cardboard	Эресписация	1EC 00329.1909-11 + AMID 1.1999-11 + AMID 2:2013-06
Ambient temperature (operation) Ambient temperature (storage/transport) Ambient temperature (assembly) -40 °C 55 °C Ambient temperature (assembly) -5 °C 100 °C Relative humidity (storage/transport) 80 % B data Number of PCB holders Type of PCB mount Total PCB surface Thickness of the PCB 1.4 mm 1.8 mm DIN rail mounting Mounting type DIN rail mounting Ckaging specifications Type of packaging packed in cardboard	Ambient conditions	
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Ambient temperature (assembly) Relative humidity (storage/transport) 80 % CB data Number of PCB holders Type of PCB mount Total PCB surface Thickness of the PCB 1.4 mm 1.8 mm DIN rail mounting Mounting type Ckaging specifications Type of packaging packed in cardboard		
Relative humidity (storage/transport) 80 % RB data Number of PCB holders Type of PCB mount Latching Total PCB surface 14200 mm² Thickness of the PCB 1.4 mm 1.8 mm DIN rail mounting kaging specifications Type of packaging packed in cardboard		
Number of PCB holders Type of PCB mount Latching Total PCB surface Thickness of the PCB 1.4 mm 1.8 mm Dunting Mounting type DIN rail mounting Ckaging specifications Type of packaging packed in cardboard		
Number of PCB holders Type of PCB mount Latching Total PCB surface 14200 mm² Thickness of the PCB 1.4 mm 1.8 mm DIN rail mounting Ckaging specifications Type of packaging packed in cardboard	Relative humidity (storage/transport)	80 %
Type of PCB mount Total PCB surface 14200 mm² Thickness of the PCB 1.4 mm 1.8 mm DIN rail mounting Ckaging specifications Type of packaging packed in cardboard	B data	
Total PCB surface 14200 mm² Thickness of the PCB 1.4 mm 1.8 mm bunting Mounting type DIN rail mounting ckaging specifications Type of packaging packed in cardboard	Number of PCB holders	2
Total PCB surface 14200 mm² Thickness of the PCB 1.4 mm 1.8 mm bunting Mounting type DIN rail mounting ckaging specifications Type of packaging packed in cardboard	Type of PCB mount	Latching
Mounting type DIN rail mounting ckaging specifications Type of packaging packed in cardboard		
Mounting type DIN rail mounting ckaging specifications Type of packaging packed in cardboard	Thickness of the PCB	1.4 mm 1.8 mm
Mounting type DIN rail mounting ckaging specifications Type of packaging packed in cardboard		
ckaging specifications Type of packaging packed in cardboard	-	
Type of packaging packed in cardboard	Mounting type	DIN rail mounting
	ckaging specifications	
	Type of packaging	packed in cardboard

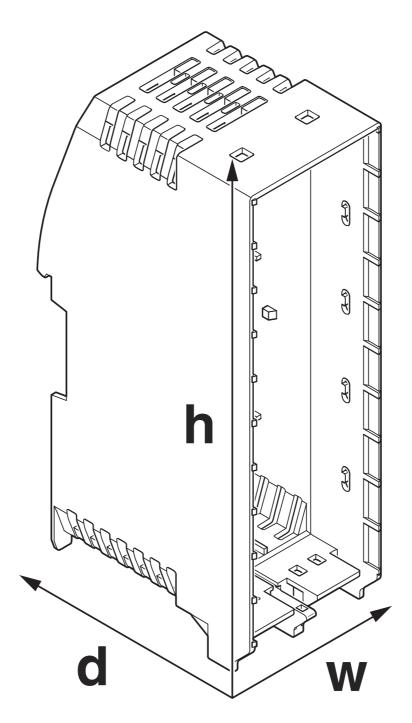


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Drawings

Dimensional drawing



Schematic figure for illustrating the item dimensions. The figure is not of the desired product. For further details, refer to the product drawings in the "Downloads" tab.



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Approvals

To download certificates, visit the product detail page: https://www.phoenixcontact.com/us/products/1103436



UL RecognizedApproval ID: E240868



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Classifications

ECLASS

	ECLASS-11.0	27182702
	ECLASS-13.0	27190601
ΕI	ГІМ	
	ETIM 9.0	EC001031
1 11	NSPSC	
UI	NOFOC	
	UNSPSC 21.0	31261500



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Environmental product compliance

EU RoHS

Fulfills EU RoHS substance requirements	Yes, No exemptions
China RoHS	
Environment friendly use period (EFUP)	EFUP-E
	No hazardous substances above the limits
EU REACH SVHC	
REACH candidate substance (CAS No.)	No substance above 0.1 wt%

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